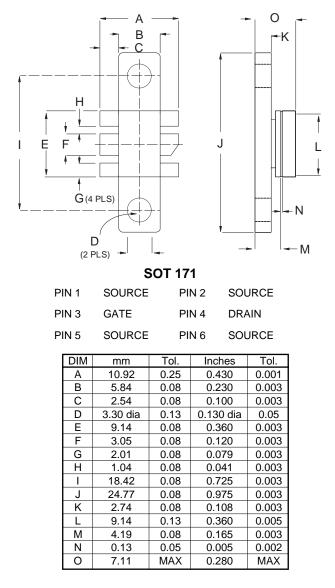
TetraFET

# D2294UK



# **ROHS COMPLIANT METAL GATE RF SILICON FET**

#### MECHANICAL DATA



# GOLD METALLISED MULTI-PURPOSE SILICON DMOS RF FET 15W – 12.5V – 500MHz SINGLE ENDED

## FEATURES

- SIMPLIFIED AMPLIFIER DESIGN
- SUITABLE FOR BROAD BAND APPLICATIONS
- VERY LOW C<sub>rss</sub>
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN 11 dB MINIMUM

## **APPLICATIONS**

• HF/VHF/UHF COMMUNICATIONS from 1 MHz to 1 GHz

# **ABSOLUTE MAXIMUM RATINGS** (T<sub>case</sub> = 25°C unless otherwise stated)

P <sub>D</sub>	Power Dissipation	50W
BV <sub>DSS</sub>	Drain – Source Breakdown Voltage	40V
BV <sub>GSS</sub>	Gate – Source Breakdown Voltage	±20V
I <sub>D(sat)</sub>	Drain Current *	12A
T <sub>stg</sub>	Storage Temperature	–65 to 150°C
Tj	Maximum Operating Junction Temperature	200°C



#### ELECTRICAL CHARACTERISTICS (T<sub>case</sub> = 25°C unless otherwise stated)

	Parameter	Test Conditions			Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain–Source	V <sub>GS</sub> = 0		10mA	40			V
	Breakdown Voltage	VGS – 0	- U		40			v
IDSS	Zero Gate Voltage	V - 12 F	E\/ \/	<sub>SS</sub> = 0			1	mA
	Drain Current	V <sub>DS</sub> = 12.5	v vGS				I	ШA
I <sub>GSS</sub>	Gate Leakage Current	$V_{GS} = 20V$	V <sub>DS</sub>	= 0			6	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage *	I <sub>D</sub> = 10mA	V <sub>DS</sub>	= V <sub>GS</sub>	1		7	V
9 <sub>fs</sub>	Forward Transconductance *	V <sub>DS</sub> = 10V	I <sub>D</sub> =	0.6A	1.08			S
G <sub>PS</sub>	Common Source Power Gain	P <sub>O</sub> = 15W			11			dB
η	Drain Efficiency	V <sub>DS</sub> = 12.5	V I <sub>DQ</sub>	= 0.6A	50			%
VSWR	Load Mismatch Tolerance	f = 500MHz	<u> </u>		20:1			_
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 0$	$V_{GS} = -5V$	f = 1MHz			72	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 12.5V	$V_{GS} = 0$	f = 1MHz			60	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>DS</sub> = 12.5V	$V_{GS} = 0$	f = 1MHz			6	pF

\* Pulse Test: Pulse Duration = 300  $\mu$ s , Duty Cycle  $\leq 2\%$ 

### HAZARDOUS MATERIAL WARNING

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area.

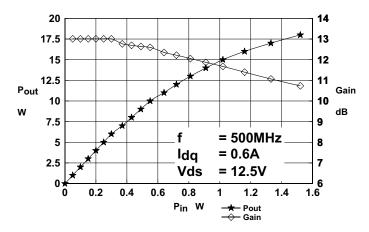
#### THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

#### THERMAL DATA

R <sub>THj-case</sub>	Thermal Resistance Junction – Case	Max.3.5°C / W
-----------------------	------------------------------------	---------------



D2294UK



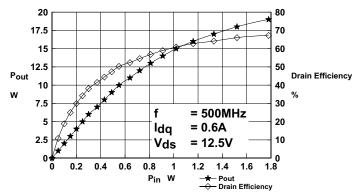
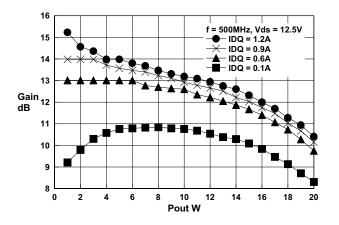


Figure 1 Output power and Gain vs. Input Power

Figure 2 Output power and Efficiency vs. Input Power



#### Figure 3 Gain vs Output Power

### **OPTIMUM SOURCE AND LOAD IMPEDANCE**

Frequency	ZL	ZS
MHz	Ω	Ω
500	1.7 + j5.7	3.3+j1.1



D2294UK

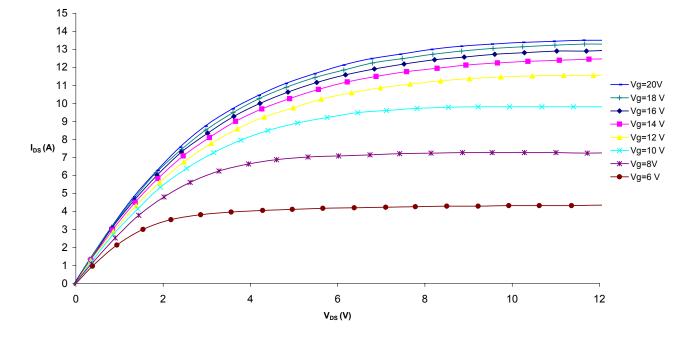
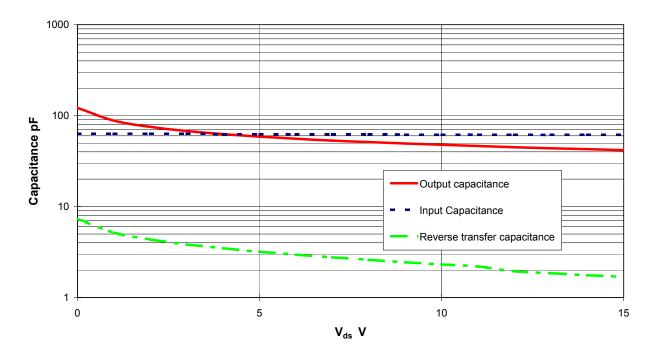


Figure 4 – Typical IV Characteristics.







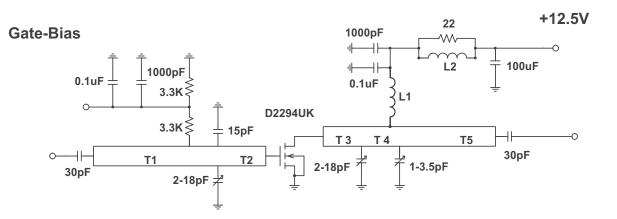
# **Typical S Parameters**

! Vds=12.5V, Idq=0.6A # MHZ S MA R 50

Freq	S11		S21		S12		S22	
MHz	mag	ang	mag	ang	mag	ang	mag	ang
70	0.73	-137	14.61	92	0.02	2	0.67	-154
100	0.74	-146	10.8	83	0.02	-3	0.69	-159
150	0.76	-154	6.86	69	0.019	-13	0.73	-163
200	0.78	-159	4.8	60	0.017	-18	0.76	-165
250	0.8	-162	3.6	52	0.015	-22	0.79	-167
300	0.82	-165	3	47	0.014	-22	0.82	-168
350	0.84	-167	2.27	38	0.012	-23	0.84	-171
400	0.86	-169	1.92	34	0.01	-23	0.86	-172
450	0.88	-171	1.52	27	0.008	-20	0.88	-174
500	0.89	-173	1.31	24	0.006	-8	0.89	-175
550	0.9	-174	1.09	19	0.006	7	0.91	-177
600	0.92	-175	0.94	12	0.006	17	0.92	-178
650	0.93	-176	0.74	12	0.006	33	0.93	-180
700	0.94	-178	0.65	7	0.007	39	0.94	179
750	0.94	-180	0.53	8	0.007	49	0.94	178
800	0.95	180	0.43	8	0.008	54	0.95	177
850	0.95	180	0.39	14	0.009	65	0.95	176
900	0.96	178	0.37	15	0.011	69	0.96	175
950	0.95	177	0.35	19	0.013	72	0.95	174
1000	0.95	177	0.34	17	0.014	71	0.96	173



D2294UK



# **500MHz Test Fixture**

Substrate 1.6mm FR4 All microstrip lines W = 2.75mm

- T1 47mm
- T2 9mm
- T3 9mm
- T4 13mm
- T5 32mm
- L1 7 turns 24swg enamelled copper wire, 2mm i.d.
- L2 1.5 turns 24swg enamelled copper wire on ferrite core